# Product End-of-Life Disassembly Instructions

**Product Category:** Monitors and Displays  
**Marketing Name / Model**  
[List multiple models if applicable.]  
HP EliteDisplay E222 21.5-inch Monitor

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
</table>

- **Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)**  
  With a surface greater than 10 sq cm  
  Quantity: 4

- **Batteries**  
  All types including standard alkaline and lithium coin or button style batteries  
  Quantity: 0

- **Mercury-containing components**  
  For example, mercury in lamps, display backlights, scanner lamps, switches, batteries  
  Quantity: 0

- **Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm**  
  Includes background illuminated displays with gas discharge lamps  
  Quantity: 1

- **Cathode Ray Tubes (CRT)**  
  Quantity: 0

- **Capacitors / condensers (Containing PCB/PCT)**  
  Quantity: 25

- **Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height**  
  Quantity: 1

- **External electrical cables and cords**  
  Quantity: 5

- **Gas Discharge Lamps**  
  Quantity: 0

- **Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)**  
  Quantity: 0

- **Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner**  
  Include the cartridges, print heads, tubes, vent chambers, and service stations.  
  Quantity: 0

- **Components and waste containing asbestos**  
  Quantity: 0

- **Components, parts and materials containing refractory ceramic fibers**  
  Quantity: 0

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EL-MF877-00  
Template Revision B

PSG instructions for this template are available at [EL-MF877-01](#)
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>Screw driver of &quot;+&quot; type</td>
</tr>
<tr>
<td>Description #2</td>
<td>Hexagonal nut screw driver for DVI and D-SUB connector</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the HINGE ASS'Y.
2. Remove the rear cover.
3. Separate the Mainframe and Panel
4. Remove the Main board and Power board
5. Remove the key board & Bezel &panel
6. 
7. 
8. 
9. 
10. 

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
# Mechanical Instructions

<table>
<thead>
<tr>
<th>Step</th>
<th>Figure</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>Remove the HINGE ASS'Y</td>
<td><img src="image1.png" alt="Image" /></td>
<td>Press the button to remove the hinge assy</td>
</tr>
<tr>
<td>The HINGE ASS'Y</td>
<td><img src="image2.png" alt="Image" /></td>
<td>The HINGE ASS'Y</td>
</tr>
<tr>
<td>Remove the REAR_COVER</td>
<td><img src="image3.png" alt="Image" /></td>
<td>Remove the screws first.</td>
</tr>
<tr>
<td><strong>Remove the REAR_COVER</strong></td>
<td>Use the tool to remove the Rear cover</td>
<td></td>
</tr>
<tr>
<td>--------------------------</td>
<td>-----------------------------------</td>
<td></td>
</tr>
<tr>
<td><strong>Separate the MAINFRAME and PANEL</strong></td>
<td>Tear out all tapes. Remove the screws and disconnect the connectors to separate the MAINFRAME and PANEL.</td>
<td></td>
</tr>
<tr>
<td><strong>Remove the MAIN BOARD and POWER BOARD</strong></td>
<td>Remove the MAYLR &amp; screws and disconnect the connectors to remove the MAIN BOARD Power board and USB board</td>
<td></td>
</tr>
</tbody>
</table>
Remove the key board & Bezel & panel

Remove the screws to separate the key board & Bezel & panel